



Press Release

Unisem Places Order With BE Semiconductor Industries N.V. For 154 ESEC Wire Bonders

Kuala Lumpur, Malaysia, November 16th, 2009 – Unisem (M) Berhad (Unisem) announced today that it has placed an order with BE Semiconductor Industries N.V. (Besi) for the delivery of 100 Esec wire bonders, following an order placed earlier this year for 54 wire bonders. These machines will be installed in Unisem's high volume semiconductor assembly and test factories in Chengdu, China and Ipoh, Malaysia and will help Unisem meet its customers' needs for increased capacity.

"We are seeing the volume demand in each of our factories continue to increase as the industry starts to recover and it is crucial that we have the equipment in place that will increase our capacity and improve our efficiency" stated C.H. Ang, group chief operating officer and executive director at Unisem.

"This order reflects the excellent business relations we have been developing with Unisem for more than ten years. Our close collaboration already begins in the product definition phase, so that we at Besi are able to match Unisem's requirements at an early stage", added Richard Blickman, President & CEO at Besi.

About BE Semiconductor Industries N.V.:

BE Semiconductor Industries N.V. designs, develops, manufactures, markets and services die sorting, flip-chip and multi-chip die bonding, wire bonding, packaging and plating equipment for the semiconductor industry's assembly operations. Its customers consist primarily of leading U.S., European and Asian semiconductor manufacturers, assembly subcontractors and industrial companies, which use its products in both array connect and conventional leadframe manufacturing processes. For more information about Besi, please visit our website at www.besi.com.

About Unisem

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. With approximately 9,000 employees

worldwide, Unisem has factory locations in Ipoh, Malaysia; Wales, United Kingdom; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about Unisem, please visit www.unisemgroup.com.

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